



# Material Composition Declaration

## EPC2016C

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	6.4 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	5.4032	84.90	87.03	848983
	Silicon oxide	7631-86-9	0.0209	0.33		3276
	Silicon nitride	12033-89-5	0.0066	0.10		1041
	Gallium nitride	25617-97-4	0.0255	0.40		3999
	Aluminum	7429-90-5	0.0407	0.64		6396
	Aluminum nitride	24304-00-5	0.0061	0.10		964
	Titanium	7440-32-6	0.0009	0.01		144
	Titanium nitride	25583-20-4	0.0036	0.06		573
	Copper	7440-50-8	0.0014	0.02		213
	Tungsten	7440-33-7	0.0011	0.02		169
	Polyimide		0.0290	0.46		4561
Under Bump Metal	Titanium	7440-32-6	0.0012	0.02	1.54	182
	Nickel	7440-02-0	0.0344	0.54		5400
	Vanadium	7440-62-2	0.0000	0.00		0
	Copper	7440-50-8	0.0622	0.98		9777
Solder Bump	Tin	7440-31-5	0.7094	11.15	11.43	111463
	Silver	7440-22-4	0.0182	0.29		2858
	Copper	7440-50-8	0.0000	0.00		0
Sum in total:			6.4	100.00	100	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.